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Patent No. 6,736,918  
Request for Cert. of Correction dated August 31, 2004  
Attorney Docket No. 1217-010666

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No. : 6,736,918 B1 Confirmation No. 8227  
Inventor(s) : Ichikawa et al.  
Issued : May 18, 2004  
Title : Process For Producing Cards  
Examiner : Sing P. Chan  
Customer No. : 28289

**Certificate**  
**SEP 09 2004**  
**of Correction**



REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT  
FOR PTO MISTAKE (37 C.F.R. 1.322(a))

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

ATTENTION: Decision and Certificate of Correction Branch  
Patent Issue Division

Sir:

In accordance with 35 U.S.C. §254, we attach hereto Form PTO/SB/44 and a copy of proof of PTO error(s) and request that a Certificate of Correction be issued in the above-identified patent. The following errors appear in the patent as printed:

Face of the patent, Column 2, under "FOREIGN PATENT DOCUMENTS", last reference: "JP 11(1999)" should read: --JP 11(1999)--.  
(See Information Disclosure Statement of July 23, 2001 and Abstract of cited reference.)

Column 3, Line 3, "BRIEF DESCRIPTION OF THE DRAWING" should read: --BRIEF DESCRIPTION OF THE DRAWINGS--.  
(See Preliminary Amendment dated April 27, 2001, Page 2, Line 13.)

Column 7, Line 29, Claim 2, "that the mount subs" should read: --that the mount substrate--.  
(See Amendment of April 17, 2003, Page 3, Claim 2, Line 4, second occurrence.)

Respectfully submitted,

WEBB ZIESENHEIM LOGSDON  
ORKIN & HANSON, P.C.

By Kent E. Baldauf  
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## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 6,736,918 <sup>B1</sup>  
DATED : May 18, 2004  
INVENTOR(S) : Ichikawa et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Face of the patent, Column 2, under "FOREIGN PATENT DOCUMENTS", last reference: "JP 11(19999)" should read: --JP 11(1999)--.

Column 3, Line 3, "BRIEF DESCRIPTION OF THE DRAWING" should read: --BRIEF DESCRIPTION OF THE DRAWINGS--.

Column 7, Line 29, Claim 2, "that the mount subs" should read: --that the mount substrate--.

{W0139842.1}  
MAILING ADDRESS OF SENDER:

The Webb Law Firm  
700 Koppers Building  
436 Seventh Avenue  
Pittsburgh, PA 15219-1818

PATENT NO. 6,736,918 <sup>B1</sup>

No. of additional copies



This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. **SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.**

*If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.*



PATENT APPLICATION  
Serial No. 09/830,490  
Attorney Docket No. 1217-010666

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 3729 :  
In re Application of :  
AKIRA ICHIKAWA ET AL. : PROCESS FOR PRODUCING CARD S  
Serial No. 09/830,490 :  
Filed April 27, 2001 :  
Examiner - Not Yet Assigned :

Pittsburgh, Pennsylvania  
July 23, 2001

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT  
BEFORE MAILING OF FIRST OFFICE ACTION

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Pursuant to 37 C.F.R. §§1.56, 1.97 and 1.98, Applicants hereby submit this Information Disclosure Statement together with a completed Form PTO-1449 and a copy of each reference cited and an English-language Abstract or English translation thereof.

No fee is believed to be due for the filing of this Information Disclosure Statement as it is being submitted before a first Office Action on the merits. Nevertheless, the Commissioner for Patents is hereby authorized to charge any additional fees which may be

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on July 23, 2001.

Kent E. Baldauf, Registration No. 25,826

(Name of Registered Representative)

Signature

07/23/2001

Date

Approved for use through 10/31/2001. OMB 0651-0031

PTO/SB/08A (08-00)

Under the Paperwork Reduction Act of 1995 no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO					
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)				Complete if Known	
				Application Number	09/830,490
				Filing Date	April 27, 2001
				First Named Inventor	Akira Ichikawa
				Group Art Unit	3729
				Examiner Name	Not Yet Assigned
				Attorney Docket Number	1217-010666
Sheet	1	of	1		

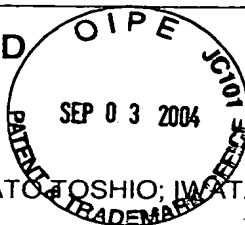
[illegible][illegible]

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language Translation is attached.

**Burden Hour Statement:** This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, D.C. 20231. **DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO:** Assistant Commissioner for Patents, Washington, D.C. 20231.

**MANUFACTURE OF IC CARD**

Patent Number: JP11221986  
Publication date: 1999-08-17  
Inventor(s): TSUDA TAKAO; KATO TOSHIO; IWATA HIDETSUGU  
Applicant(s): KONICA CORP  
Requested Patent:  $\Sigma$  JP11221986  
Application Number: JP19980027221 19980209  
Priority Number(s):  
IPC Classification: B42D15/10 ; G06K19/07 ; G06K19/077  
EC Classification:  
Equivalents:

**Abstract**

**PROBLEM TO BE SOLVED:** To manufacture a non-contact type IC card having excellent smoothness of a front surface and excellent reliability of securely disposed components in a simple step.  
**SOLUTION:** The method for manufacturing an IC card in which a component including an IC chip is placed at a predetermined position between two opposed boards and a resin is filled comprises the steps of adhering a resin selected from a thermosetting resin, hot-melt resin and ultraviolet curable resin on both sides simultaneously or respective sides subsequently of a sheet placing the component including the IC chip, and then laminating the boards. And, the boards are laminated by heating or pressurizing.

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PATENT APPLICATION

Serial No. 09/830,490

Attorney Docket No. 1217-010666

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 3729

In re Application of

AKIRA ICHIKAWA ET AL.

PROCESS FOR PRODUCING CARD 5

Serial No. 09/830,490

Filed April 27, 2001

Examiner - Not Yet Assigned

Pittsburgh, Pennsylvania

July 23, 2001

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT  
BEFORE MAILING OF FIRST OFFICE ACTION

Commissioner for Patents  
Washington, D.C. 20231

Sir:

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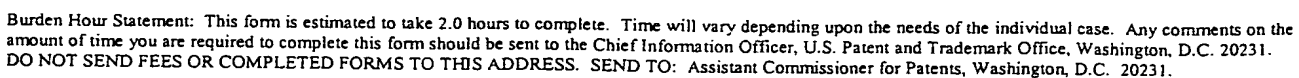
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231 on July 23, 2001.

Kent E. Baldauf, Registration No. 25,826

(Name of Registered Representative)

Signature

07/23/2001  
Date



SEP 03 2004

## Abstract

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PATENT APPLICATION

Serial No. 09/830,490

Attorney Docket No. 1217-010666

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 3729

In re Application of

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**MANUFACTURE OF IC CARD**

Patent Number: JP11221986  
Publication date: 1999-08-17  
Inventor(s): TSUDA TAKAO; KATO TOSHIO; IWATA HIDETSUGU  
Applicant(s):: KONICA CORP  
Requested Patent: 特 許 出 願 第 JP11221986  
Application Number: JP19980027221 19980209  
Priority Number(s):  
IPC Classification: B42D15/10 ; G06K19/07 ; G06K19/077  
EC Classification:  
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